

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3002297

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JOHN GLENN EDELEN	08/26/2014
NICOLE SEMLER	08/27/2014
MICHAEL MARRA	08/27/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	FUNAI ELECTRIC CO., LTD
<b>Street Address:</b>	7-7-1, NAKAGAITO, DAITO-SHI
<b>City:</b>	OSAKA
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	5740013
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14472297
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	35968-1048
<b>NAME OF SUBMITTER:</b>	BENJAMIN M. HALPERN
<b>SIGNATURE:</b>	/Benjamin M. Halpern/
<b>DATE SIGNED:</b>	08/28/2014
<b>Total Attachments: 3</b>	
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ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNORS of good and valuable consideration, the receipt of which is hereby acknowledged,

ASSIGNORS:

(1) Full Name of Inventor: John Glenn EDELEN

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(2) Full Name of Inventor: Nicole SEMLER

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(3) Full Name of Inventor: Michael MARRA

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hereby sell, assign and transfer to ASSIGNEE:

FUNAI ELECTRIC CO., LTD.  
7-7-1, Nakagaito, Daito-Shi  
Osaka 5740013  
JAPAN

and the successors, assigns, and legal representatives of the ASSIGNEE, the entire right, title, and interest for the United States and its territorial possessions, and in all foreign countries and regions, including all rights to claim priority, in and to the invention entitled:

**CHIP LAYOUT TO ENABLE MULTIPLE HEATER CHIP VERTICAL RESOLUTIONS**

that was invented by ASSIGNORS, and which is being filed herewith in the U.S. Patent and Trademark Office, and any legal equivalent thereof in any foreign country or region, including the right to claim priority, including any and all improvements disclosed therein, and in and to all Letters Patent to be obtained for said invention by the above application, or any continuation, continuation-in-part, divisional, renewal, or substitute thereof, and, as to Letters Patent, any reissue or reexamination or other post issuance proceedings thereof.

ASSIGNORS hereby covenant that no assignment, sale, agreement, or encumbrance has been, or will be, made or entered into which would conflict with this Assignment.

ASSIGNORS authorize ASSIGNEE to make applications for, and to receive, Letters Patent for said invention in any of said countries or regions, in ASSIGNEE'S name, or in ASSIGNOR'S name, at ASSIGNEE'S election.

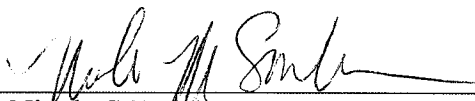
ASSIGNORS covenant and agree to execute or procure any further necessary assurance of the title to said invention, and any Letters Patent which may issue therefore, and to, at any time, upon the request and at the expense of ASSIGNEE, deliver any testimony in any interference, derivation proceeding, litigation, or proceeding related thereto, and to execute all papers that may be necessary or desirable to perfect the title to said invention, or any Letters Patent which may be granted therefore in ASSIGNEE, its successors, assigns, or other legal representatives, and to, at any time, upon the request and at the expense of ASSIGNEE, execute any continuation, continuation-in-part, divisional, renewal, or substitute thereof, and, as to Letters Patent, any reissue or reexamination or other post issuance proceedings thereof, or any other additional applications for Letters Patent for said invention or any part thereof, in any of said countries or regions, all of which applications and any Letters Patent issuing thereon are hereby assigned to ASSIGNEE, will make all rightful oaths or declarations, and do all lawful acts requisite for procuring the same therein, without further compensation, but at the expense of ASSIGNEE, its successors, assigns, or other legal representatives.

ASSIGNORS authorize and request the Commissioner of Patents to issue any and all Letters Patent of the United States of America for said invention, resulting from the aforesaid application, to FUNAI ELECTRIC CO., LTD., as its ASSIGNEE.


WITNESS my hand and seal on:

  
\_\_\_\_\_  
John Glenn EDELEN

8-26-14  
Date

  
\_\_\_\_\_  
Nicole SEMLER

AUGUST 27, 2014  
Date

  
\_\_\_\_\_  
Michael MARRA

8-27-14  
Date